

Cristian Pira

Plasma Electrolytic Polishing
as a promising treatment replacement
of Electropolishing in the Cu and Nb
substrate preparation **for SRF**

SRF 2021

July 1, 2021 THOTEV06



Work supported by the INFN CSNV experiment TEFEN

Introduction and motivation

Is there a better option than EP?



Introduction and motivation

Is there a better option to EP?

- ➔ **Nb SRF cavity polishing requires hydrofluoric acid (HF)**
 - ➔ HF is an extremely dangerous and poisoning acid
 - ➔ Serious workers hazard risks
 - ➔ Expensive procurement and disposal
 - ➔ Expensive infrastructure for safe handling



Introduction and motivation

Is there a better option to EP?

- ➔ **Nb SRF cavity polishing requires hydrofluoric acid (HF)**
- ➔ **EP without HF has been explored with different levels of success**

Introduction and motivation

Is there a better option to EP?

- ➔ **Nb SRF cavity polishing requires hydrofluoric acid (HF)**
- ➔ **EP without HF has been explored with different levels of success**

Plasma Electrolytic Polishing (PEP)

Outline

**PEP
introduction**

**PEP - EP
comparison**

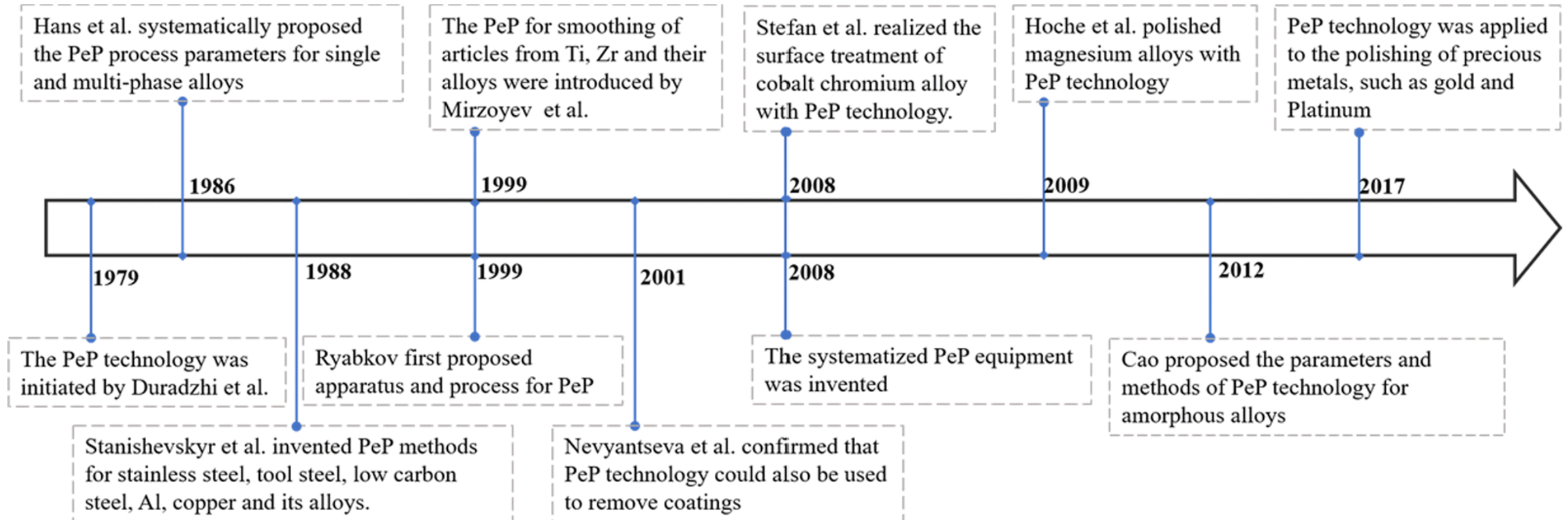
**Results
on Nb**

**Results
on Cu**

Scalability

Conclusion

Hystorical overview



Huang, Y. et al., Int J Adv Manuf Technol 114, 2021

Applications

In principle any metal can be treated

Commonly polished, available recipes



Stainless steel alloys
Brass, Bronze
Cr, Ni, Co, Mo, W, Zn alloys

Not well studied, challenging applications



Nb
Cu and its alloys
V, Ti and its alloys



CoCr knee cap



Stainless steel

Henning Zeidler et al. / Procedia CIRP 49 (2016)



Brass

Klaus Nestler et al. / Procedia CIRP 42 (2016)



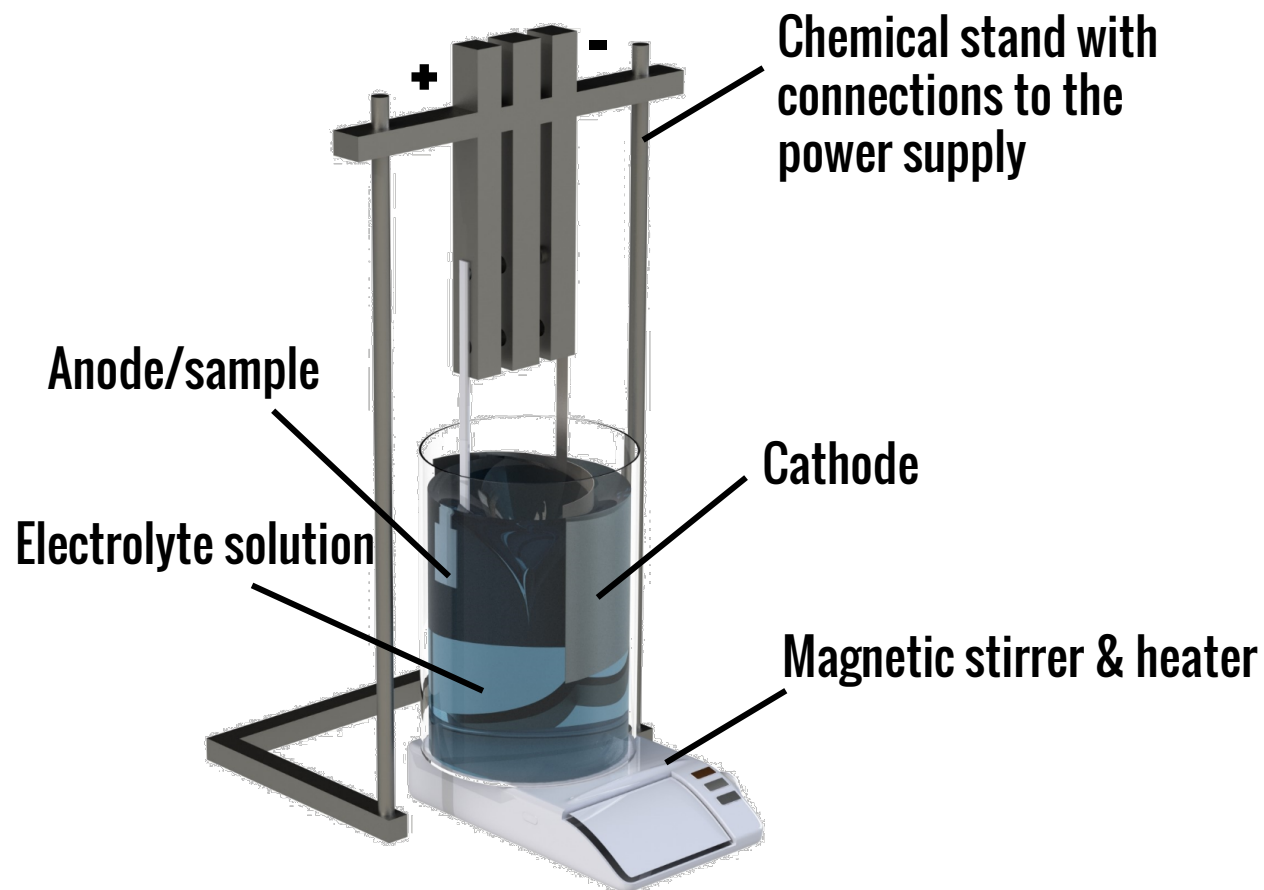
Ti alloy
(Grade 5)

*Yu. G. Aliakseyeu et al.,
Nauka i Tekhnika, 2018*

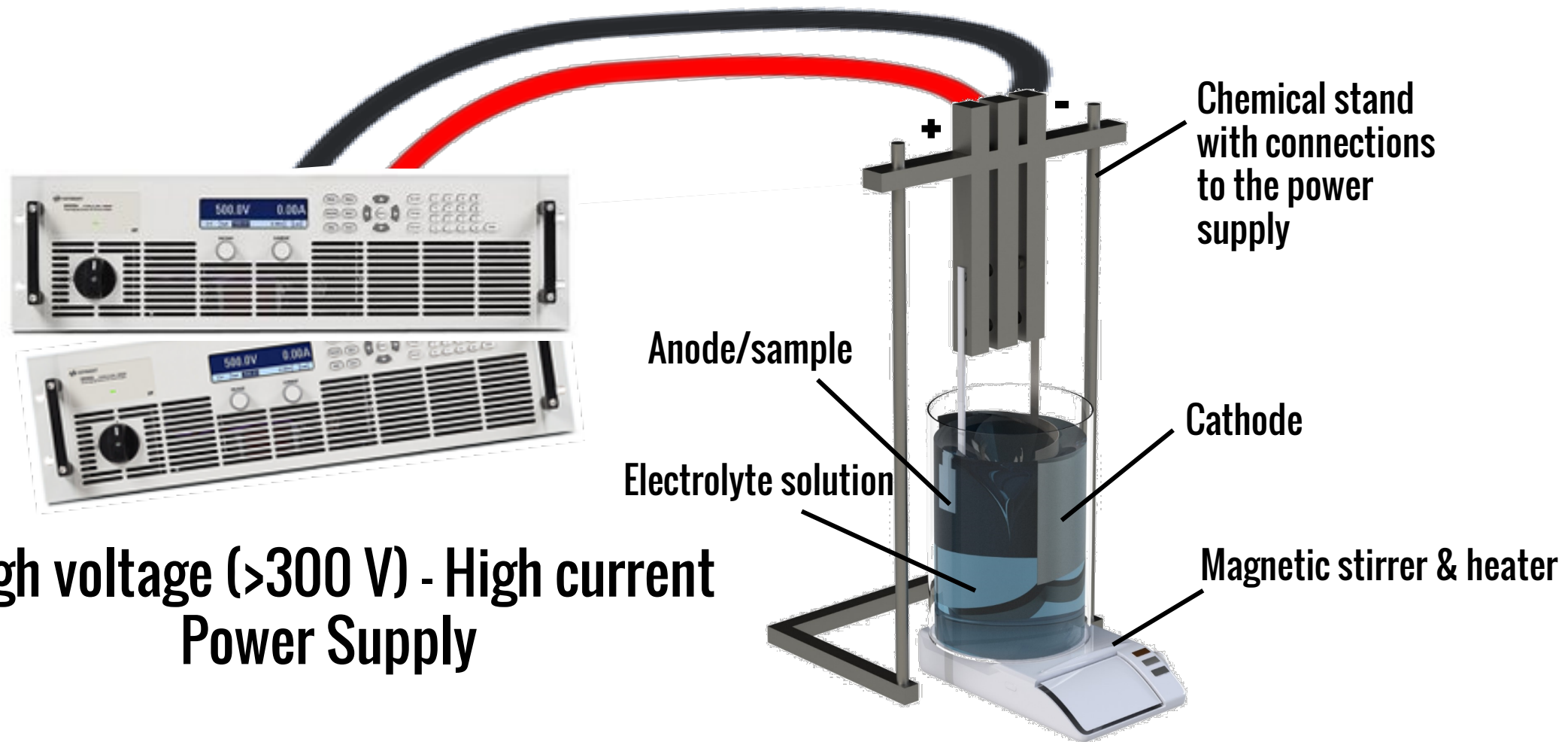
Plasma Electrolytic Polishing set-up

Identical EP set-up

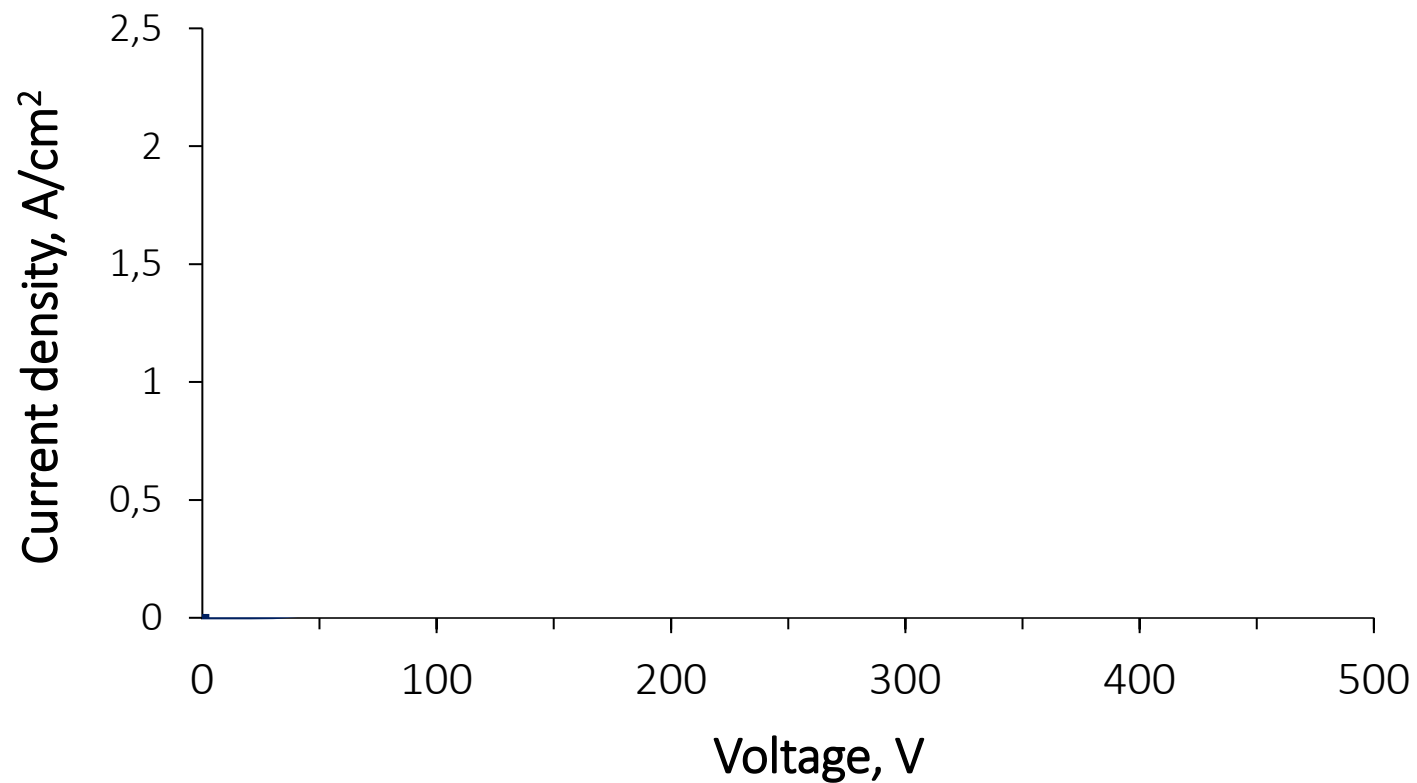
Except for...



Plasma Electrolytic Polishing set-up

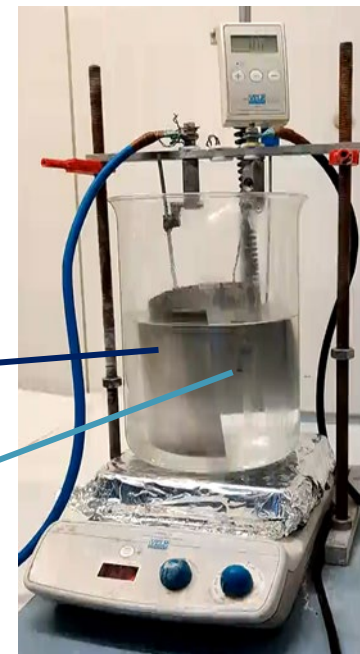


Current-voltage characteristics

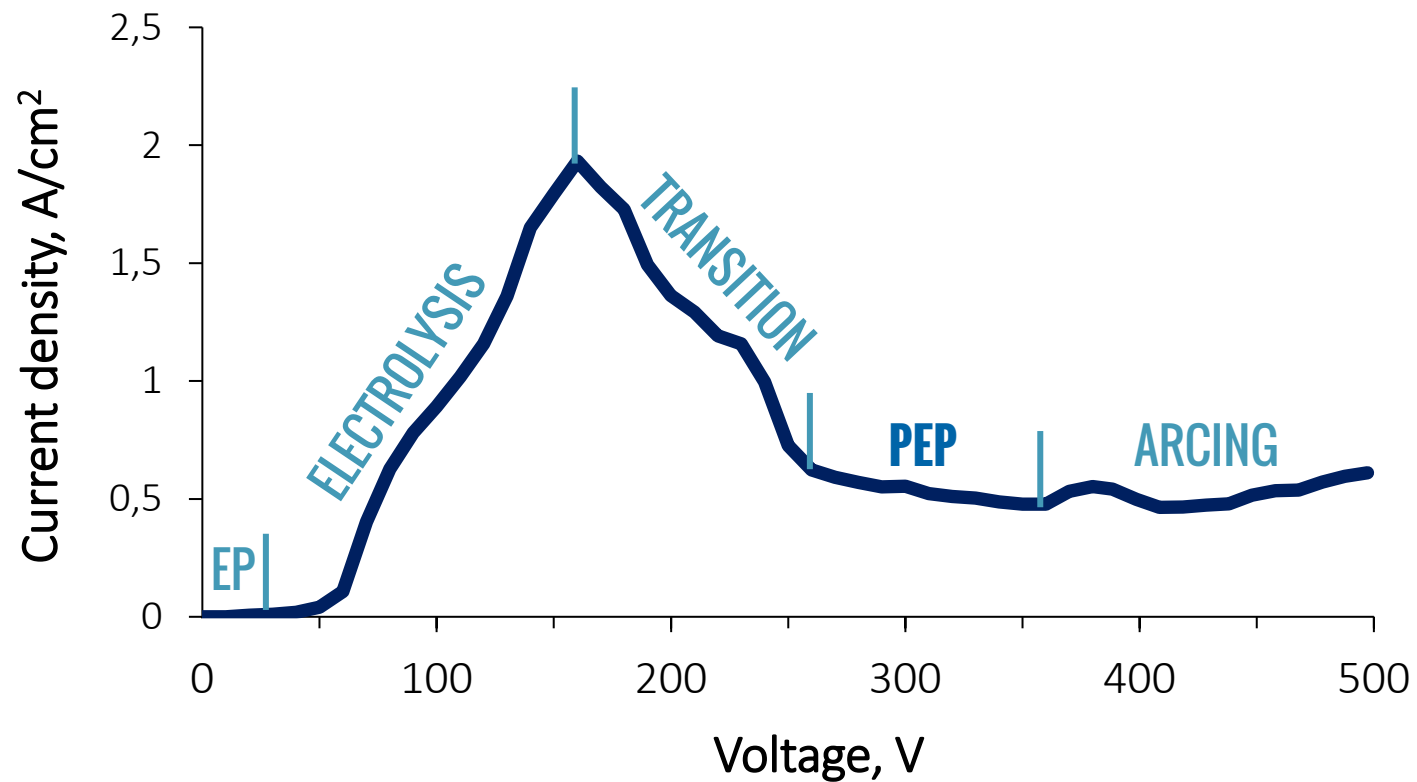


Cathode

Anode/
sample



Current-voltage characteristic



PEP Mechanism

Not fully understood yet

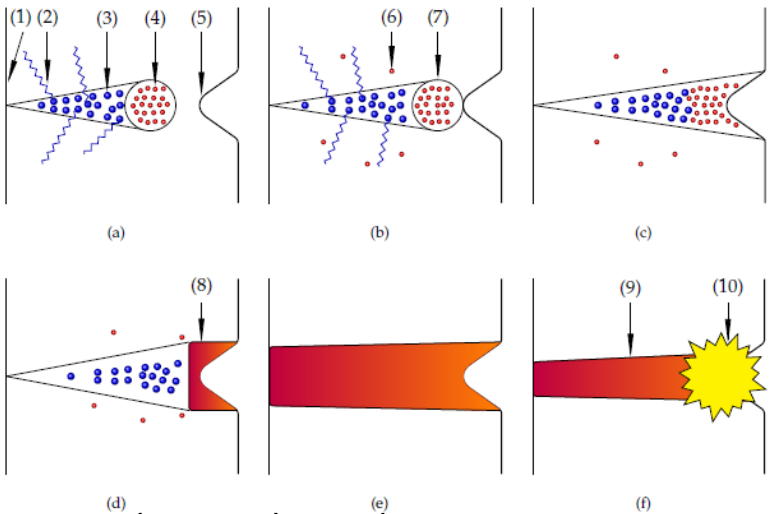
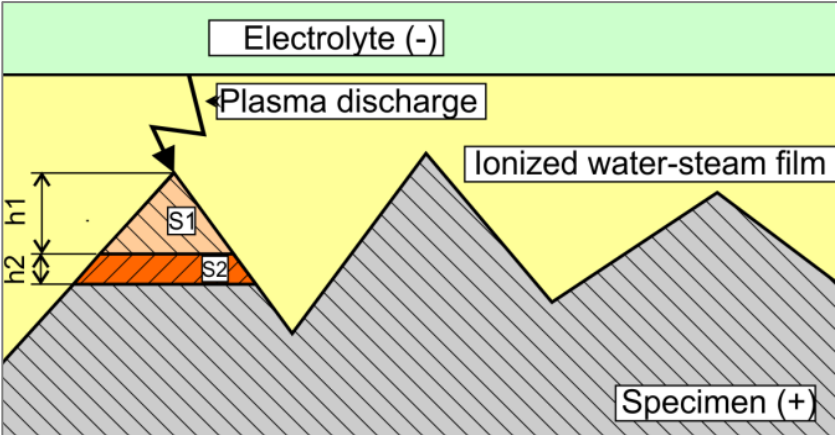
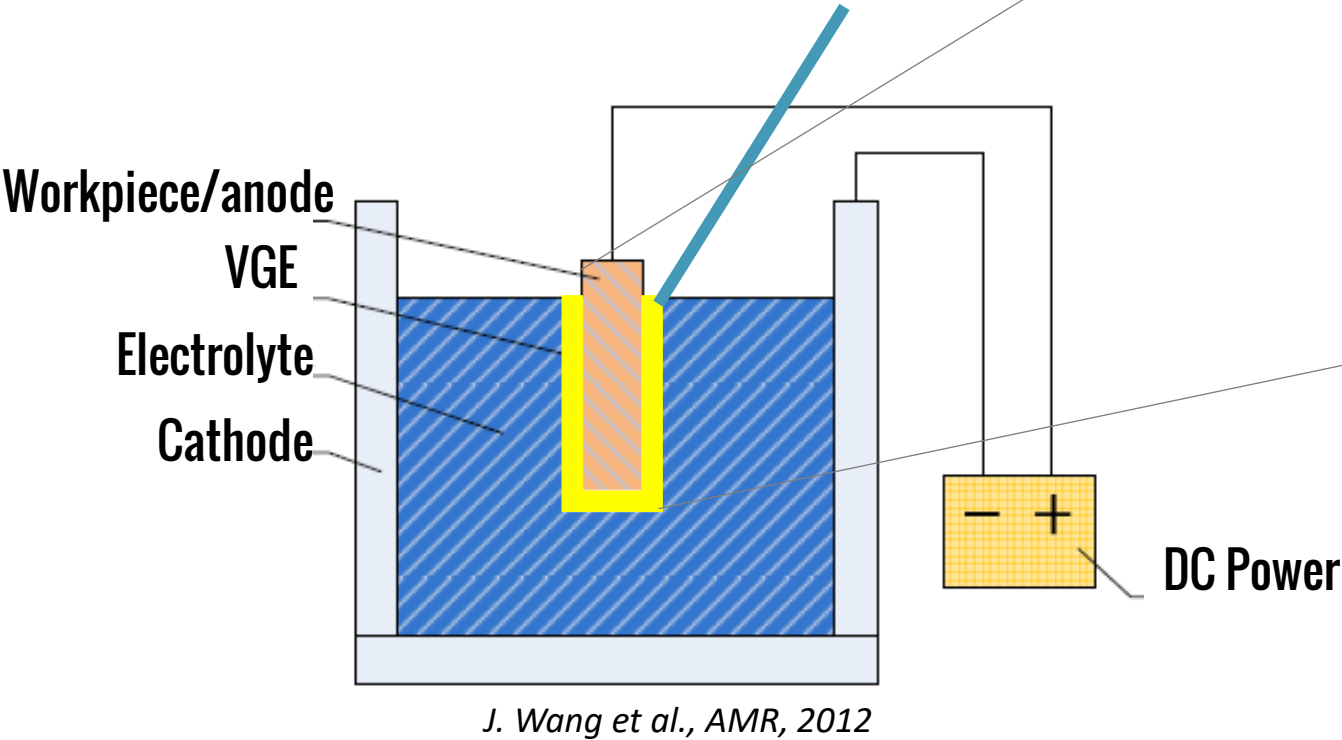


Different models proposed



PEP Mechanism

Formation of a **Vapor Gas Envelope (VGE)**
also called **Ionized Water-Steam film**



Risk assessment comparison

BCP 1:1:2	EP Nb 1:9	PEP Nb
Quantity of chemicals (w. %)		
79 %	93 %	~5%
Acids, harsh chemicals		
3 Acids: HF:HNO ₃ :H ₃ PO ₄	2 Acids: HF:H ₂ SO ₄	No acids! Only salts

Risk assessment comparison

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Risk $\propto$ Probability $\propto$ Process Time (Time to remove 200 μ m)		
~4 h	~6-10 h	~1 h

Comparison EP VS PEP

Parameters	Conventional EP	Plasma Electrolytic Polishing
Pre-treatment	In some cases mechanical pre-treatment	Not required
Roughness	0.2-0.1 μm	Achievable up to 0.01 μm
Cathode	Should follow the shape of the piece	Shape is not important
Electrolytes	Harsh electrolytes, concentrated acids	Greener, diluted water based salts (1-10%)
Time to remove 100 μm	3 h - 7 h	15-30 min
Voltage	2-60 V	260-360 V
Temperature	Room temperature	> 65°C
Current density	0,01-0,04 A/cm ²	0,2-0,6 A/cm ²

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Results
on Nb

Results
on Cu

Trials and optimization

Almost 30 different solutions tested

No satisfying results with solutions in literature for Nb and Cu

1 original Solution for Nb and 2 for Cu have been optimized
(currently under patenting evaluation)

Parameters studied:
voltage, conductivity, working temperature, cathode shape



Processes parameters comparison

Process / parameters	BCP (1:1:2)	EP (1:9)
Solution composition	HF:HNO ₃ :H ₃ PO ₄	HF:H ₂ SO ₄
Voltage	-	18 V
Current density	-	0.025 A/cm ²
Power density	-	0.45 W/cm ²
Removing rate	1 μm/min (15 °C)	0.3 μm/min (30 °C)

Processes parameters comparison

Process / parameters	BCP (1:1:2)	EP (1:9)	PEP
Solution composition	HF:HNO ₃ :H ₃ PO ₄	HF:H ₂ SO ₄	Diluted salts
Voltage	-	18 V	300 V
Current density	-	0.025 A/cm ²	0.4-0.6 A/cm ²
Power density	-	0.45 W/cm ²	~150 W/cm ²
Removing rate	1 µm/min (15 °C)	0.3 µm/min (30 °C)	3.5 µm/min (78 °C)

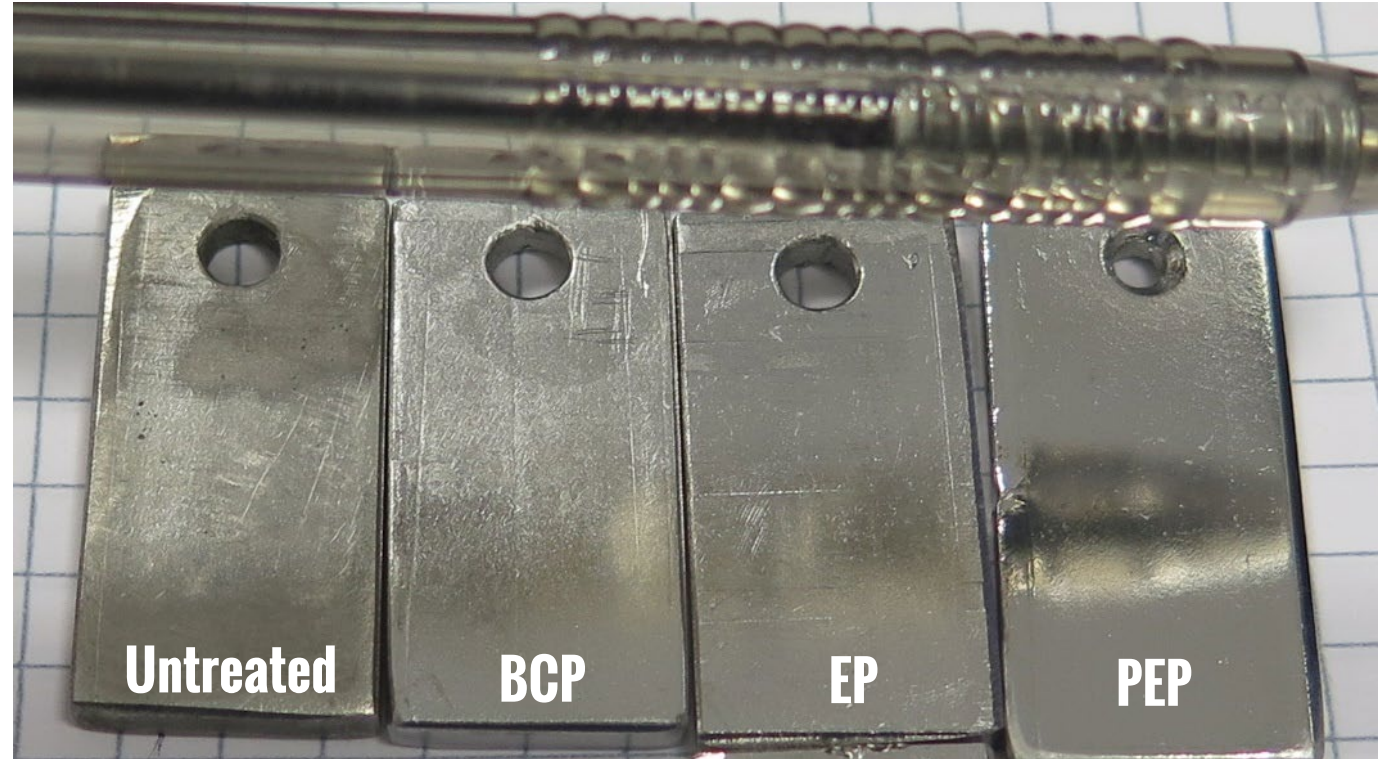

3.5 times faster than BCP


>10 times faster than EP

Fast polishing test



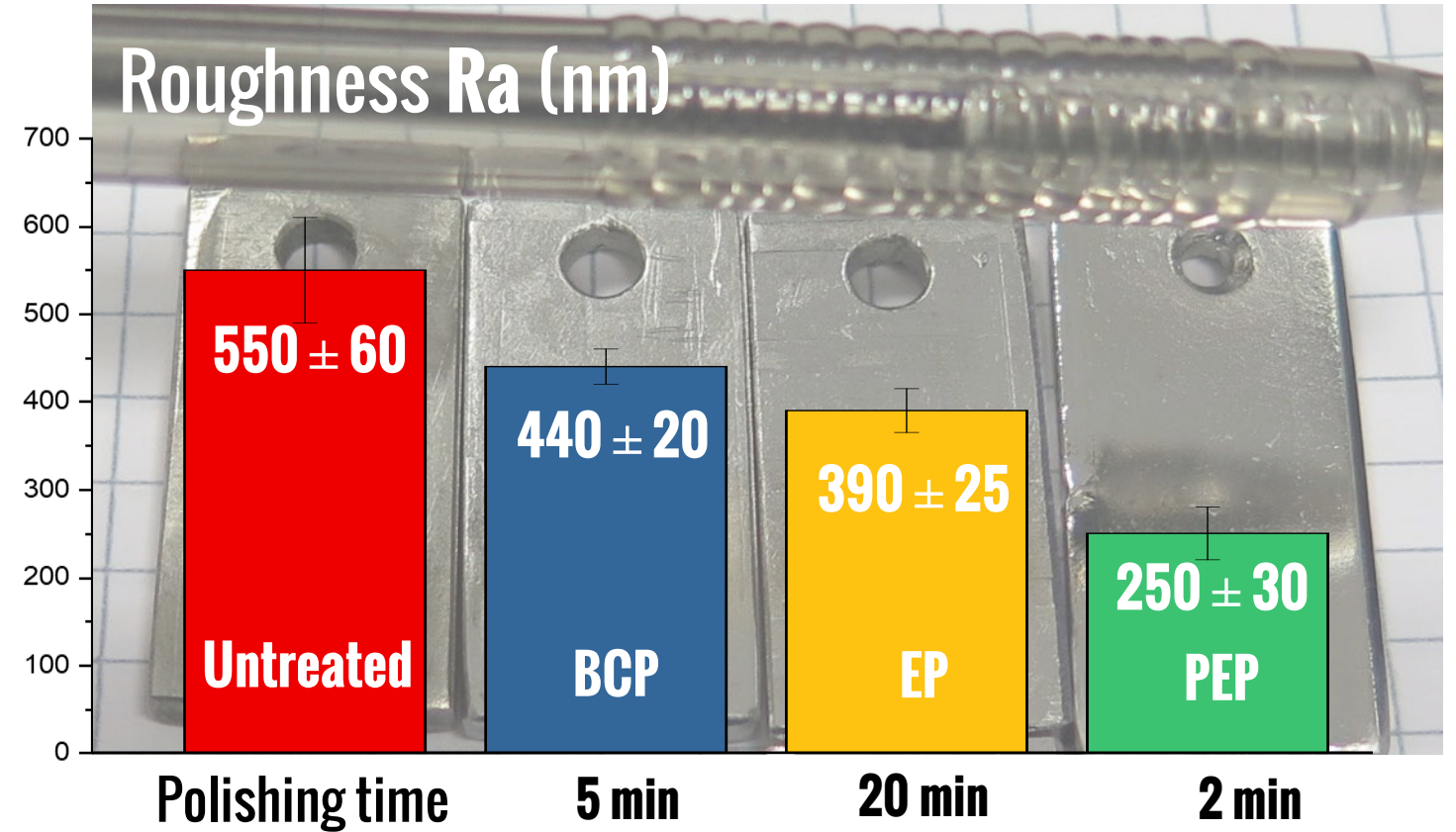
$6.5 \pm 0.5 \mu\text{m}$
removed



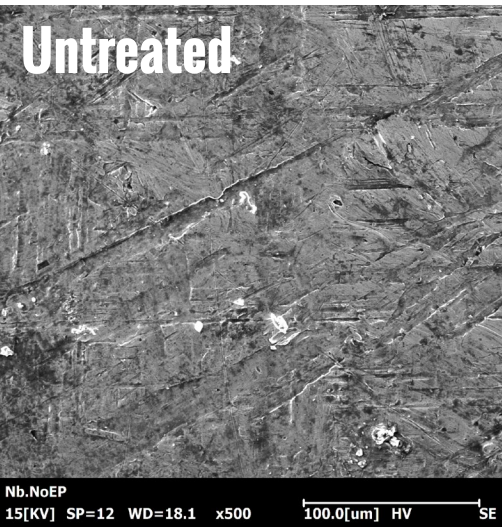
Fast polishing test



$6.5 \pm 0.5 \mu\text{m}$
removed

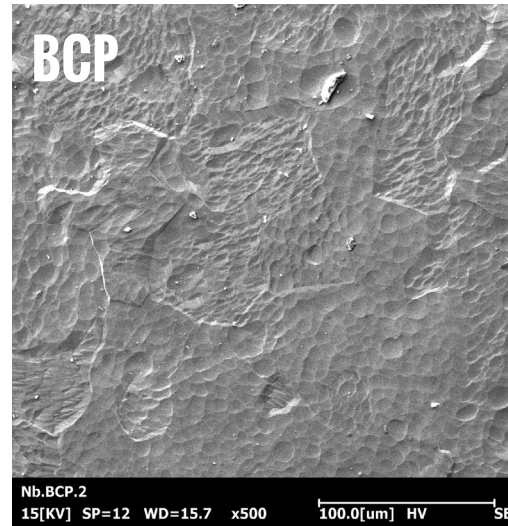


Fast polishing test

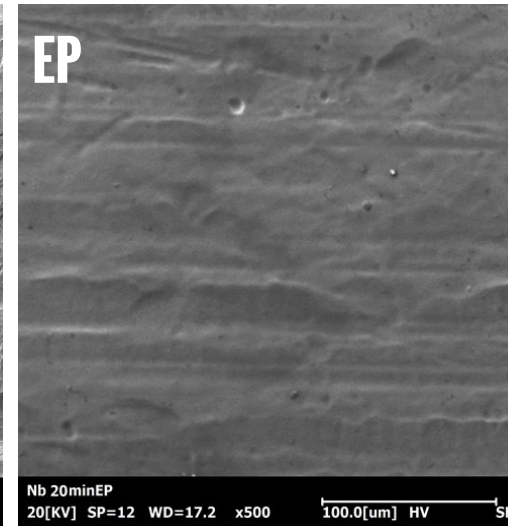


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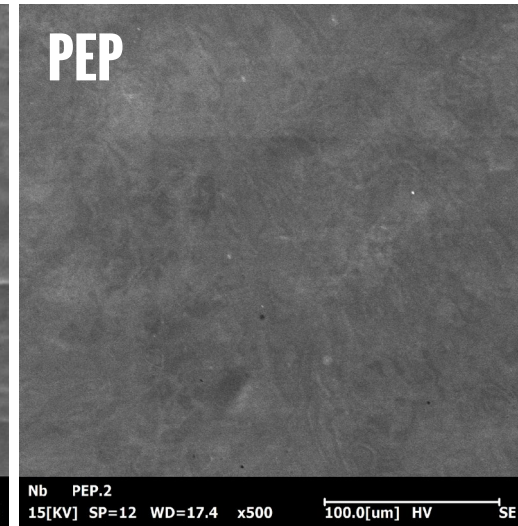
Polishing time



5 min

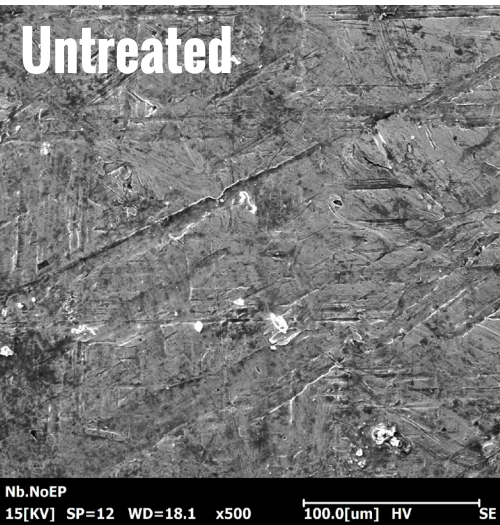


20 min

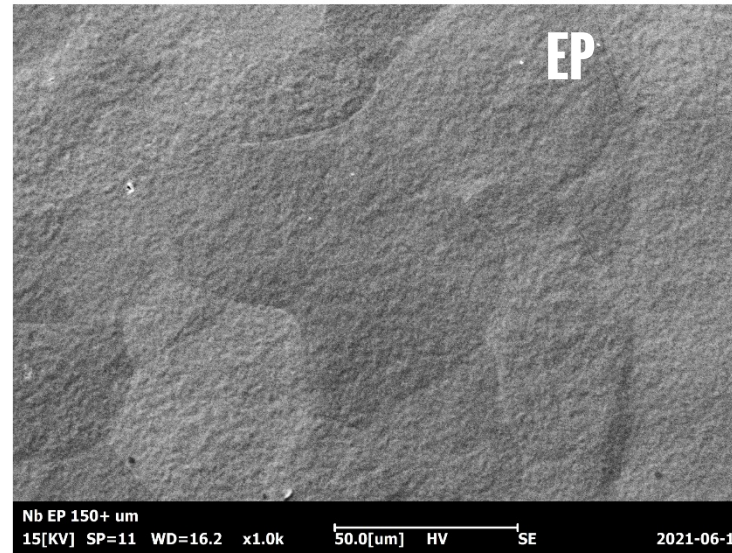


2 min

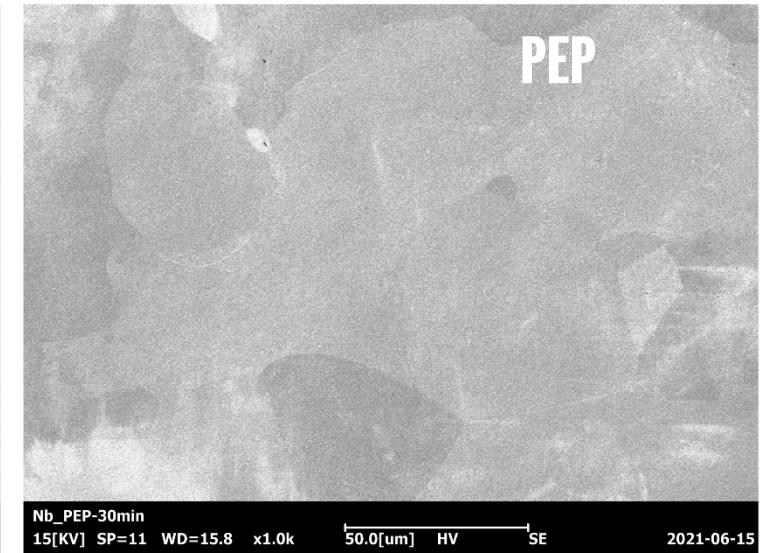
Long polishing test



~ 150 μm
removed



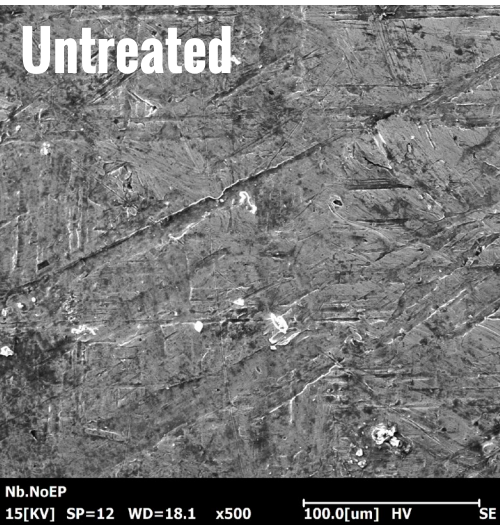
150 μm ~ 5 h



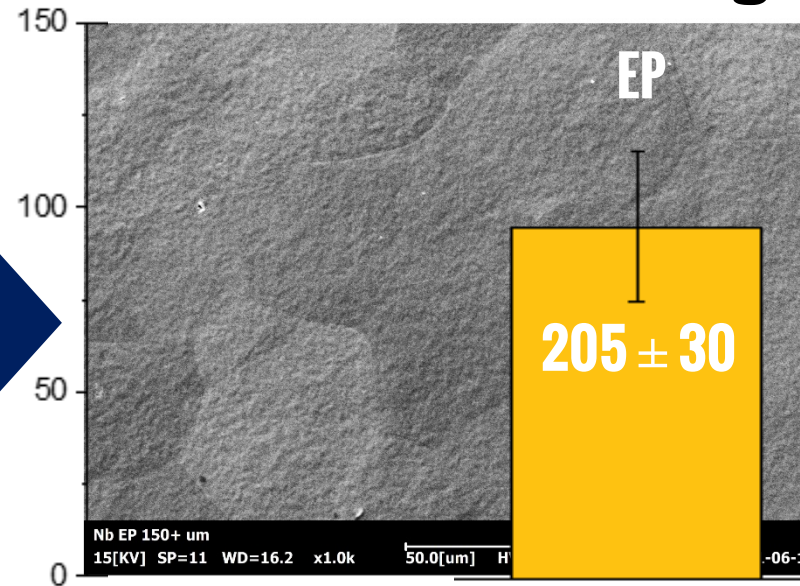
150 μm ~ 40 min

Long polishing test

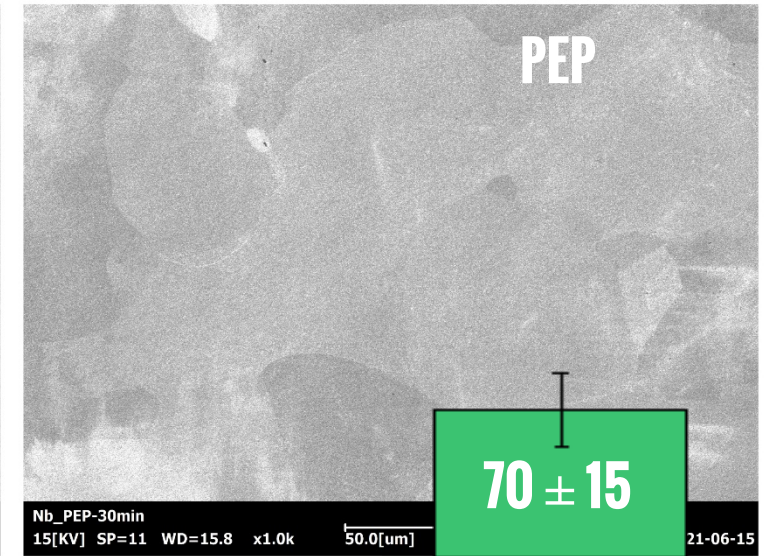
Roughness Ra (nm)



~ 150 μm
removed



150 μm ~ 5 h



150 μm ~ 40 min

Processes parameters comparison

Process / parameters	SUBU5	EP (3:2)
Solution composition	Sulfamic acid 5 g/l; NH ₄ -citrate 1 g/l Butanol 50 ml/l; H ₂ O ₂ 50 ml/l	85 % H ₃ PO ₄ : n-Butanol
Voltage	-	2-6 V
Current density	-	0,01 - 0,03 A/cm ²
Power draw	-	0,12 W/cm ²
Removing rate	1,5 μm/min (70 ± 2°C)	0,15-0,5 μm/min (25°C)

Processes parameters comparison

Process / parameters	SUBU5	EP (3:2)	PEP
Solution composition	Sulfamic acid 5 g/l; NH ₄ -citrate 1 g/l Butanol 50 ml/l; H ₂ O ₂ 50 ml/l	85 % H ₃ PO ₄ : n-Butanol	Diluted salts
Voltage	-	2-6 V	300 V
Current density	-	0,01 - 0,03 A/cm ²	0,35-0,45 A/cm ²
Power draw	-	0,12 W/cm ²	135 W/cm ²
Removing rate	1,5 μm/min (70 ± 2°C)	0,15-0,5 μm/min (25°C)	3-10 μm/min (70-80°C)



PEP

~ 3 times faster than SUBU5



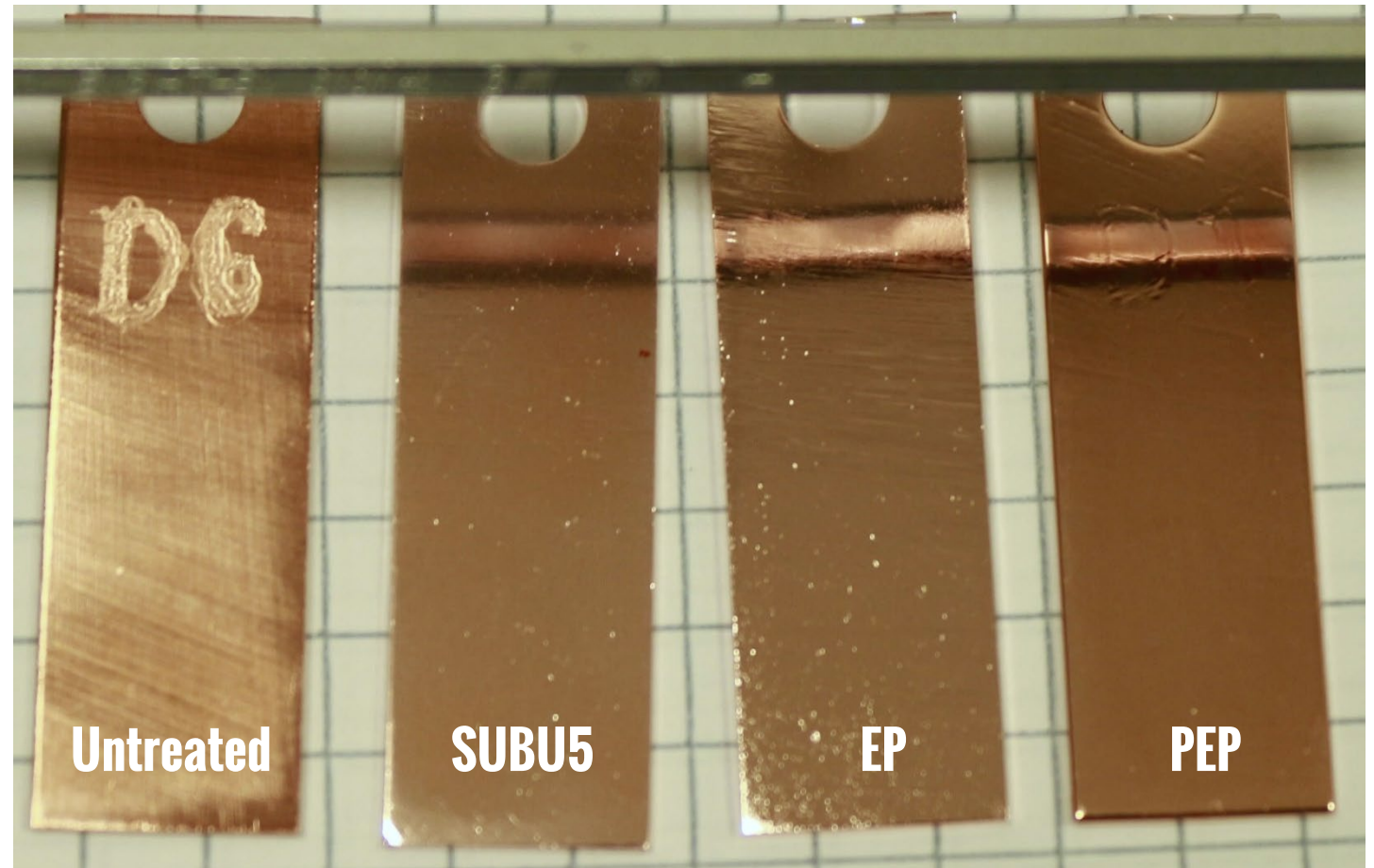
PEP

10-20 times faster than EP

Fast polishing test



$8 \pm 0.5 \mu\text{m}$
removed

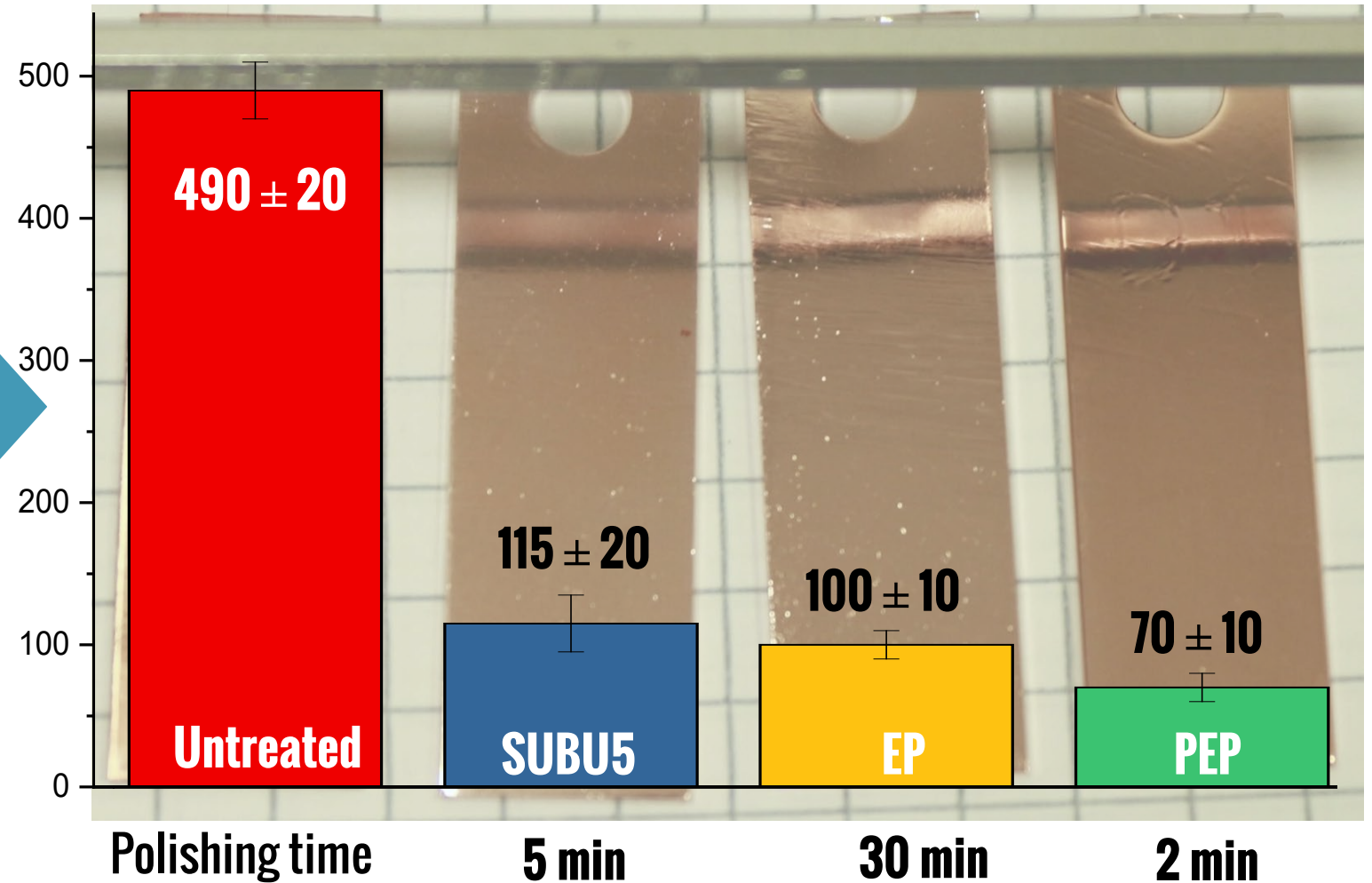


Fast polishing test

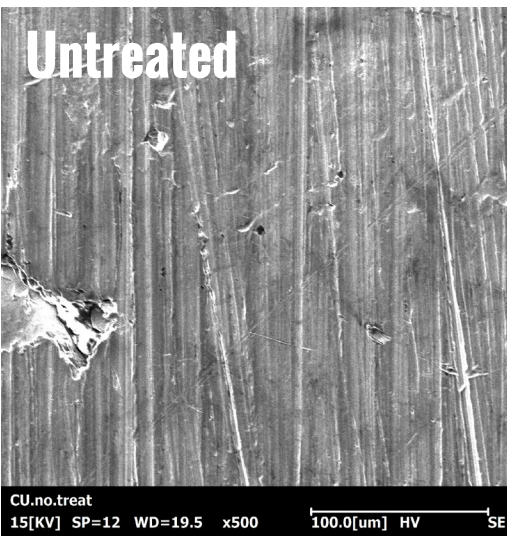
Roughness R_a (nm)



$8 \pm 0.5 \mu\text{m}$
removed

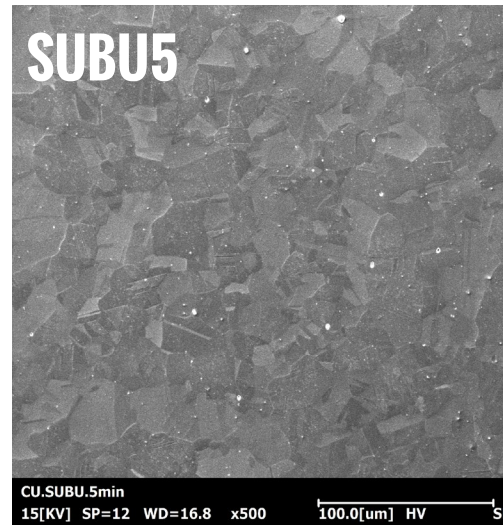


Fast polishing test

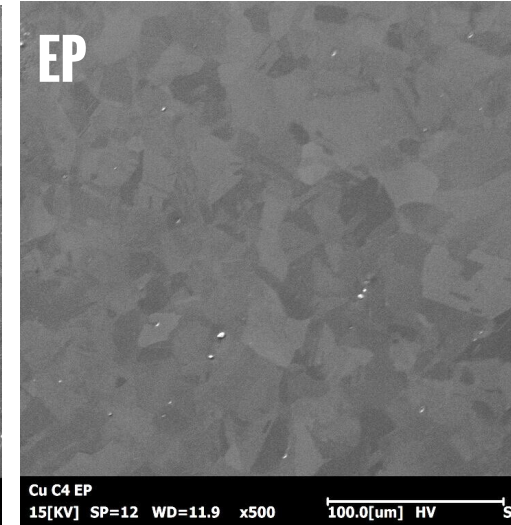


$8 \pm 0.5 \mu\text{m}$
removed

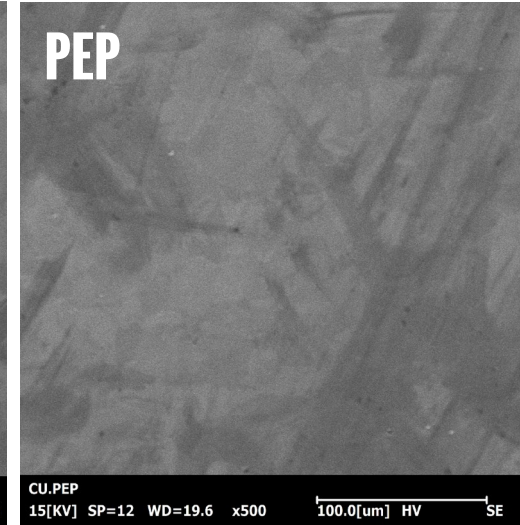
Polishing time



5 min



30 min

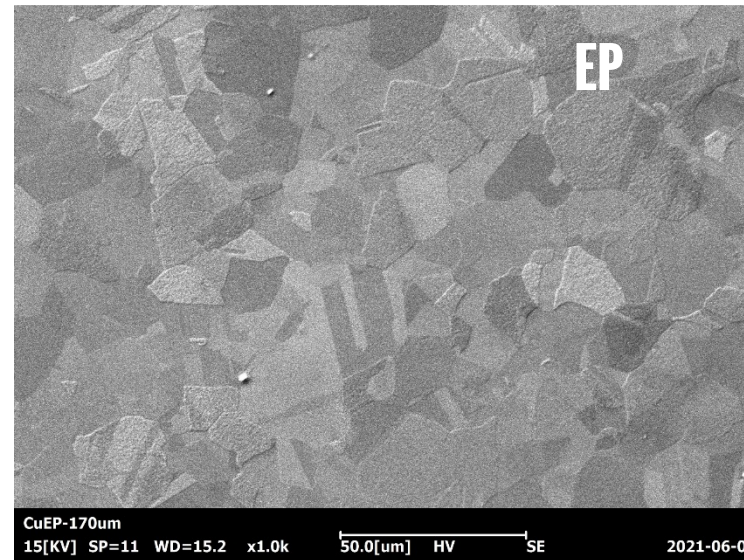


2 min

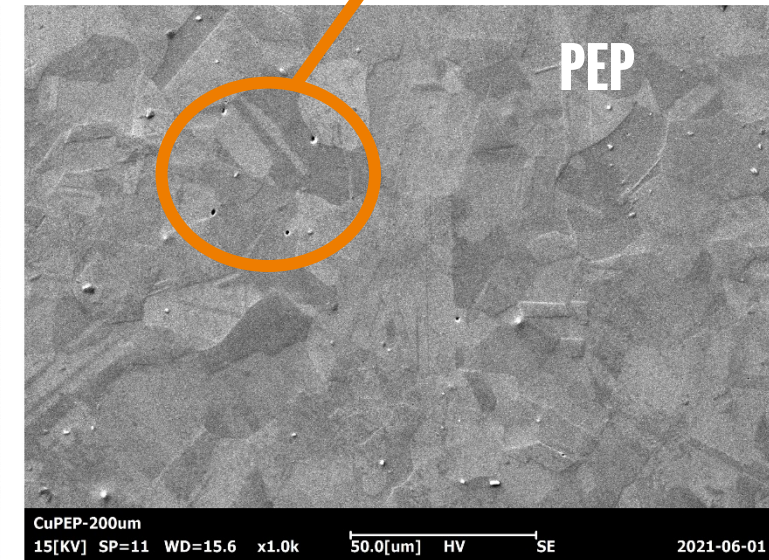
Long polishing test



>170 μm
removed



170 μm ~ 5 h



Pitting on a small portion

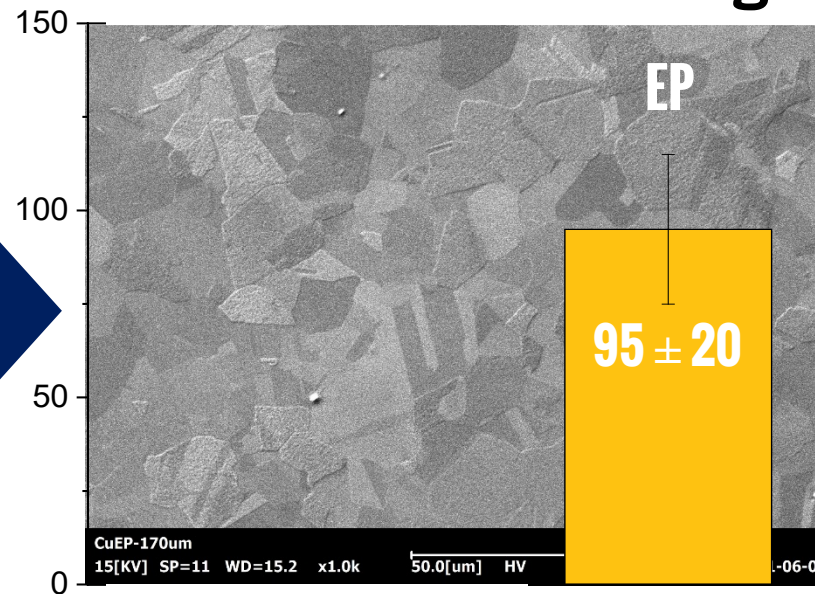
200 μm ~ 40 min

Long polishing test

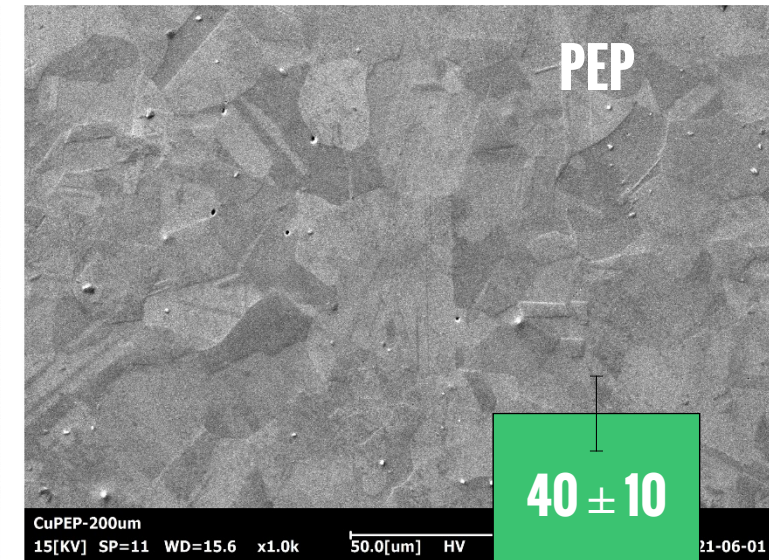
Roughness Ra (nm)



>170 μm
removed



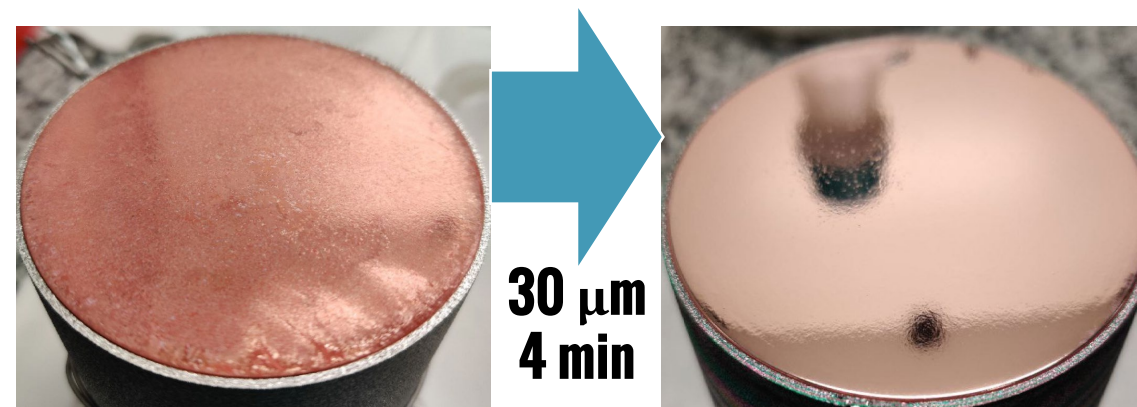
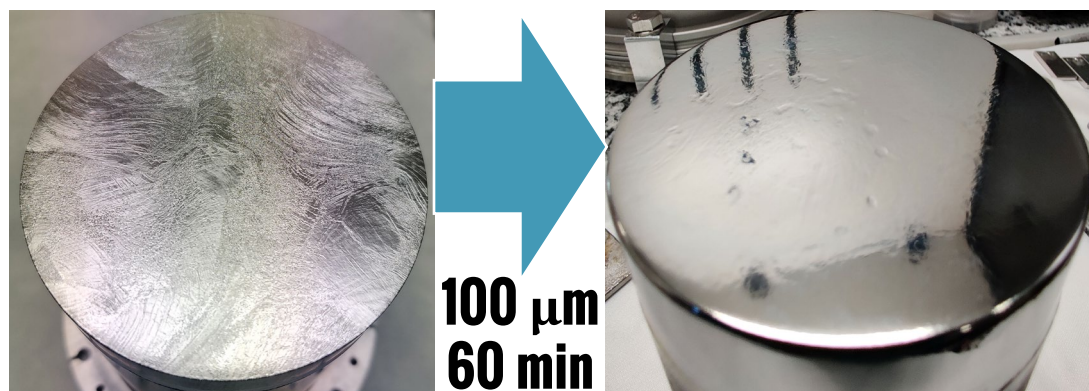
170 μm ~ 5 h



200 μm ~ 40 min

Real samples treatment

PEP tested on HZB Quadrupole Resonators
(not tested yet)



Eduard Chyhyrynets

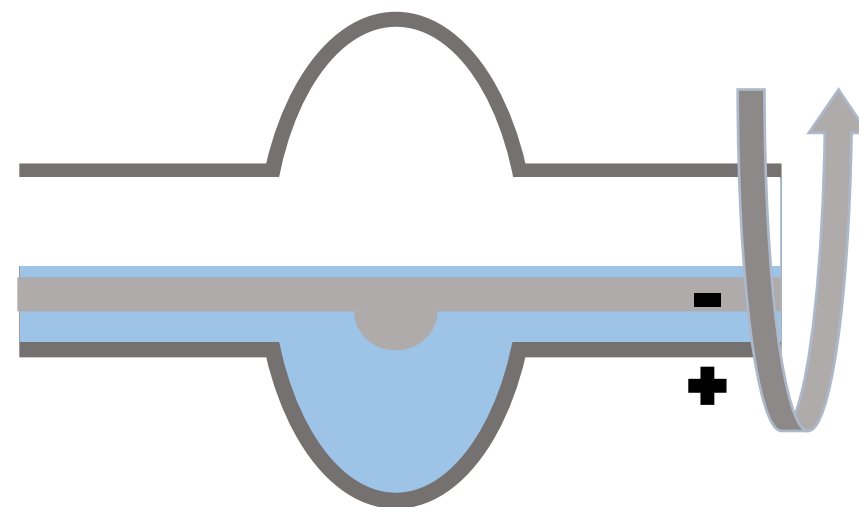
SUPTEV002 Application of Plasma Electrolytic Polishing onto SRF Substrates

SRF 2021
Student Poster Session

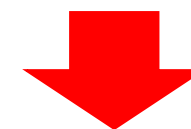
Scalability

Scalability to large areas is very challenging:

- ➔ High power demand
- ➔ Large amounts of gases produced



Single cell 1.3 GHz in horizontal configuration



~ 20 kW in PEP regime

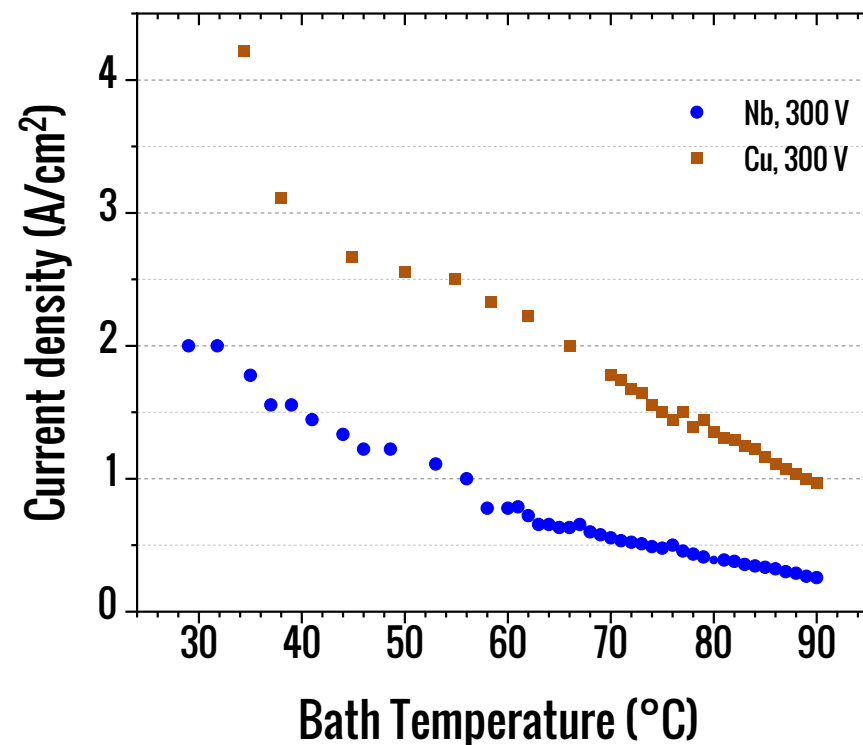
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Possible solutions to explore:

- ➔ Pulsed PEP
- ➔ Increase bath temperature
- ➔ Lowering voltage after triggering the plasma



Scalability

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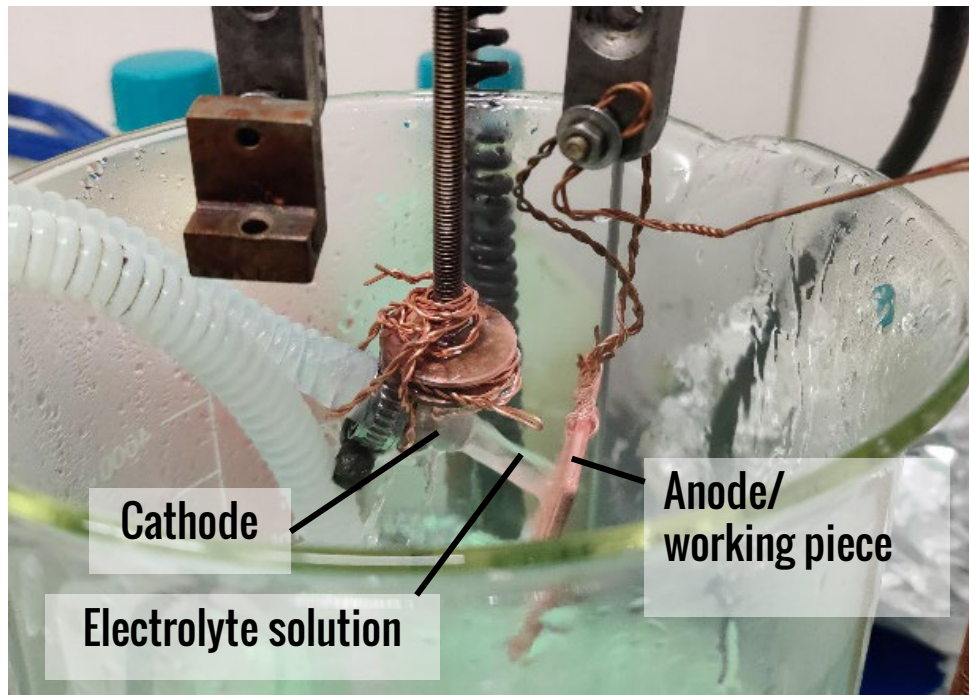
- ➔ High power demand
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Possible solutions to explore:

- ➔ Pulsed PEP
- ➔ Increase bath temperature
- ➔ Lowering voltage after triggering the plasma
- ➔ **Jet-polishing**

Jet-Plasma Electrolytic Polishing

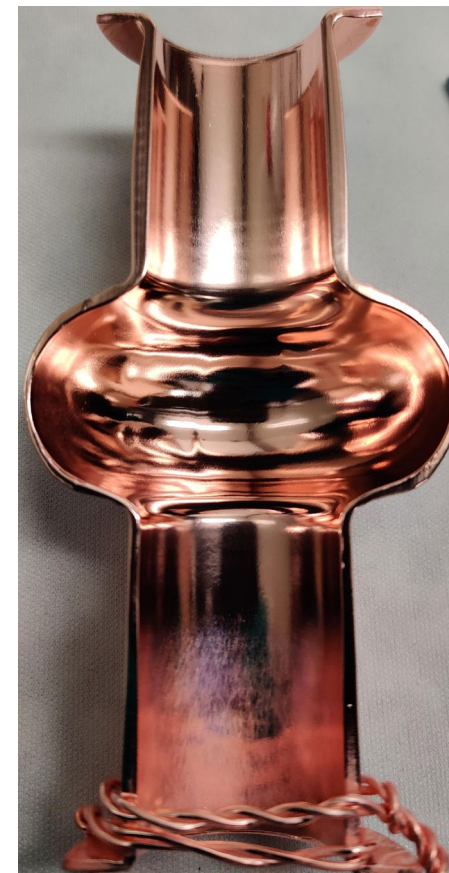
Local polishing for large area treatments



Jet-PEP set-up



Half 6 GHz Untreated



Half 6 GHz JET-PEP polished

Conclusions

Polishing via PEP of Nb and Cu possible

- ➡ Smoother surface than EP
- ➡ Safer and more eco-friendly than EP
- ➡ 10 times faster than EP
- ➡ Polishing of large areas challenging ➡ Jet-PEP possible

SRF 2021



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and **Eduard Chyhyrynets**

Thank you for the attention!

